



US00D475682S

(12) **United States Design Patent**  
**Li et al.**

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(45) **Date of Patent:** **\*\* Jun. 10, 2003**

(54) **OPTICAL SUB-ASSEMBLY MODULE**

D355,406 S \* 2/1995 Smith ..... D13/133  
6,299,467 B1 \* 10/2001 Chien ..... 439/188

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\* cited by examiner

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(57) **CLAIM**

(\*\*) Term: **14 Years**

The ornamental design for an optical sub-assembly module,  
as shown and described.

(21) Appl. No.: **29/161,112**

**DESCRIPTION**

(22) Filed: **May 24, 2002**

(30) **Foreign Application Priority Data**

Feb. 8, 2002 (TW) ..... 91300598

(51) **LOC (7) Cl.** ..... **13-02**

(52) **U.S. Cl.** ..... **D13/133**

(58) **Field of Search** ..... D13/133; 361/395;  
362/363; 439/188, 668, 567, 490, 541.5,  
79, 83, 871

FIG. 1 is a front elevational view of an optical sub-assembly module showing our new design;

FIG. 2 is a rear elevational view thereof;

FIG. 3 is a left side elevational view thereof;

FIG. 4 is a right side elevational view thereof;

FIG. 5 is a top plan view thereof;

FIG. 6 is a bottom plan view thereof; and,

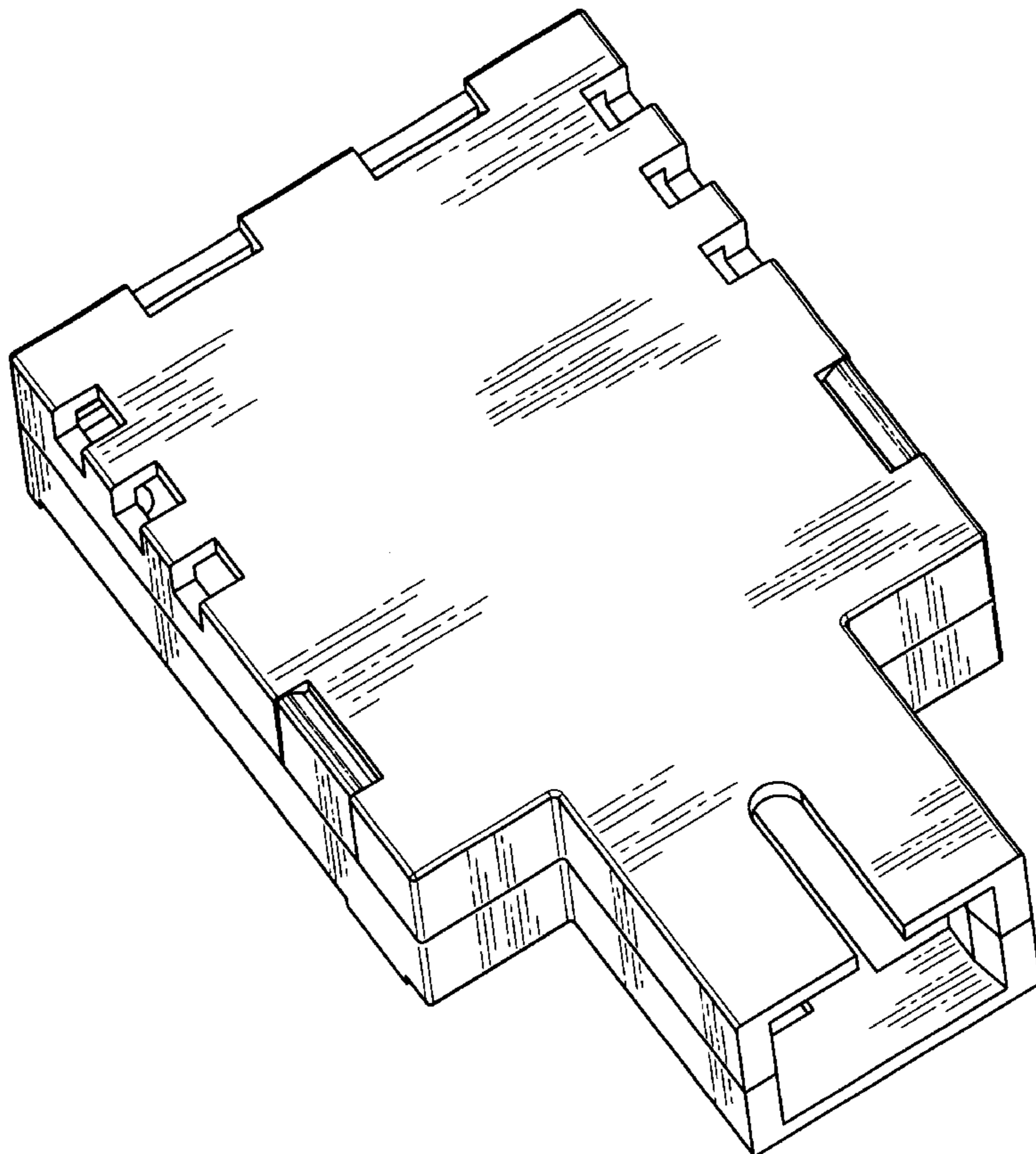
FIG. 7 is a perspective view thereof.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

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**1 Claim, 4 Drawing Sheets**



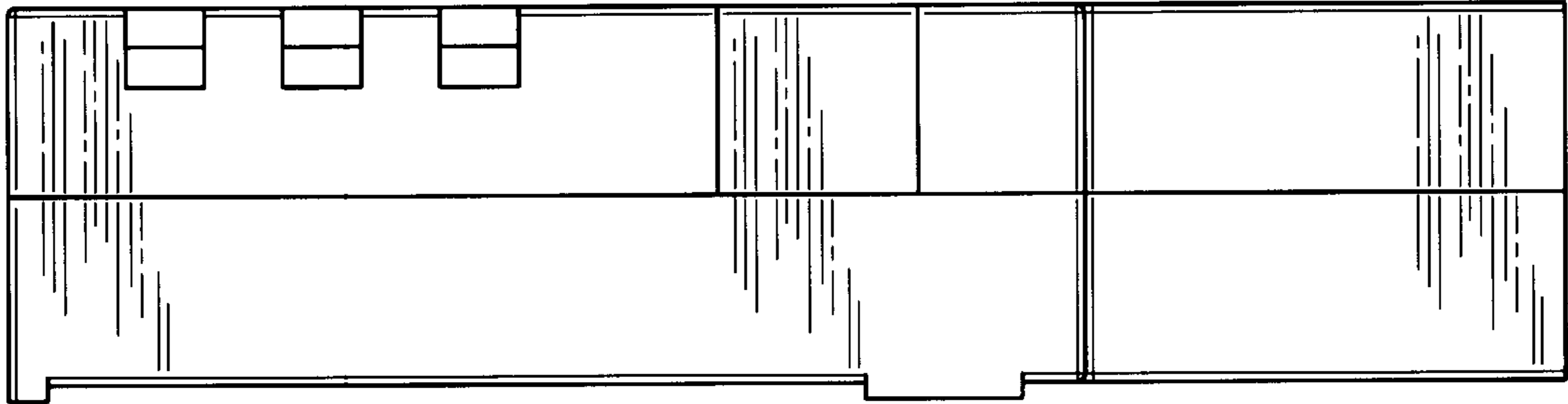


Fig. 1

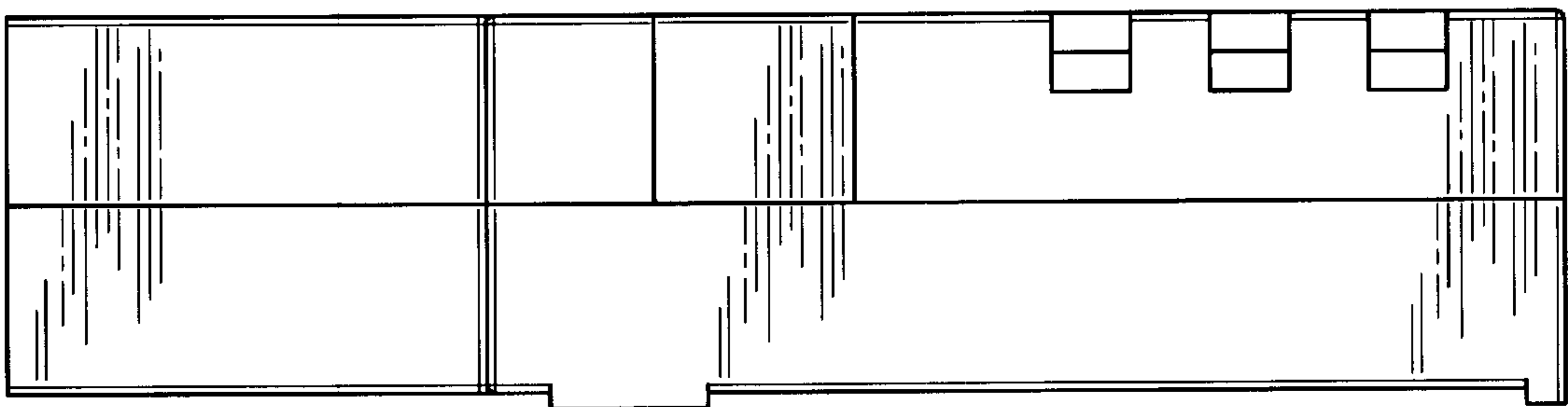


Fig. 2

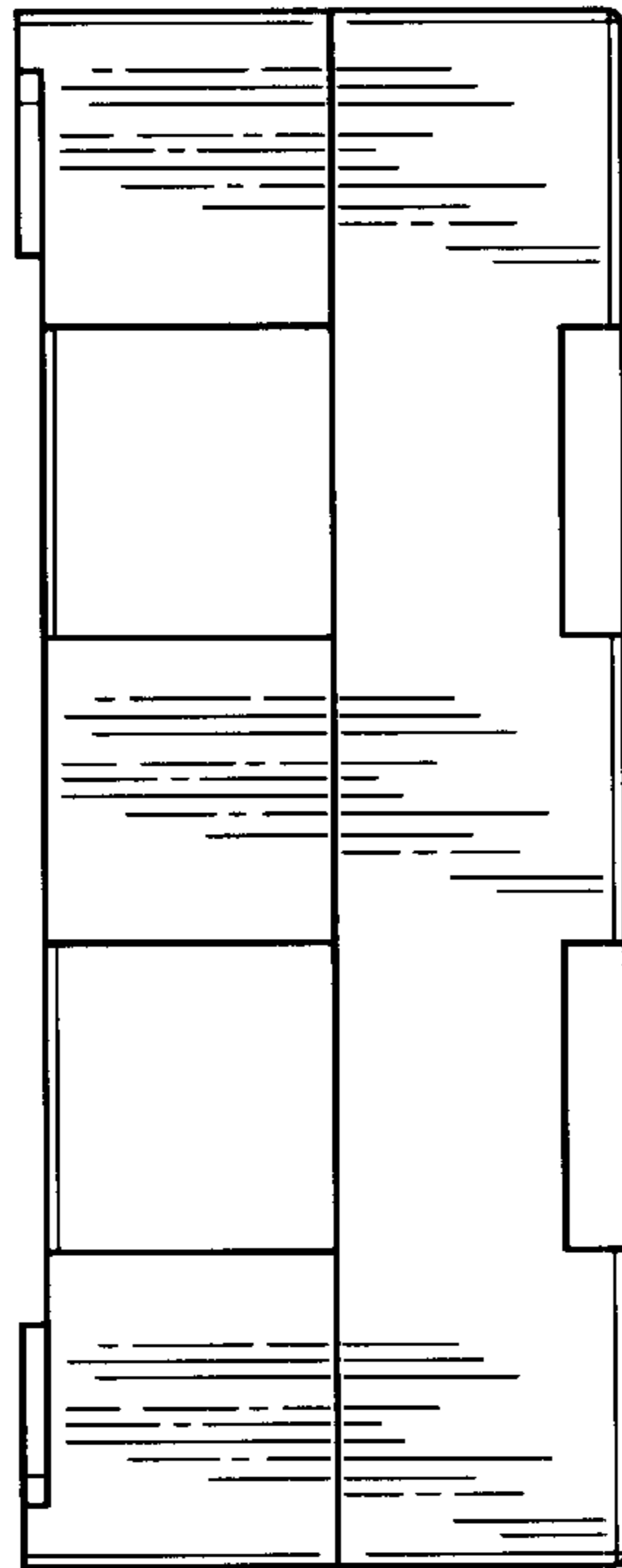


Fig. 3

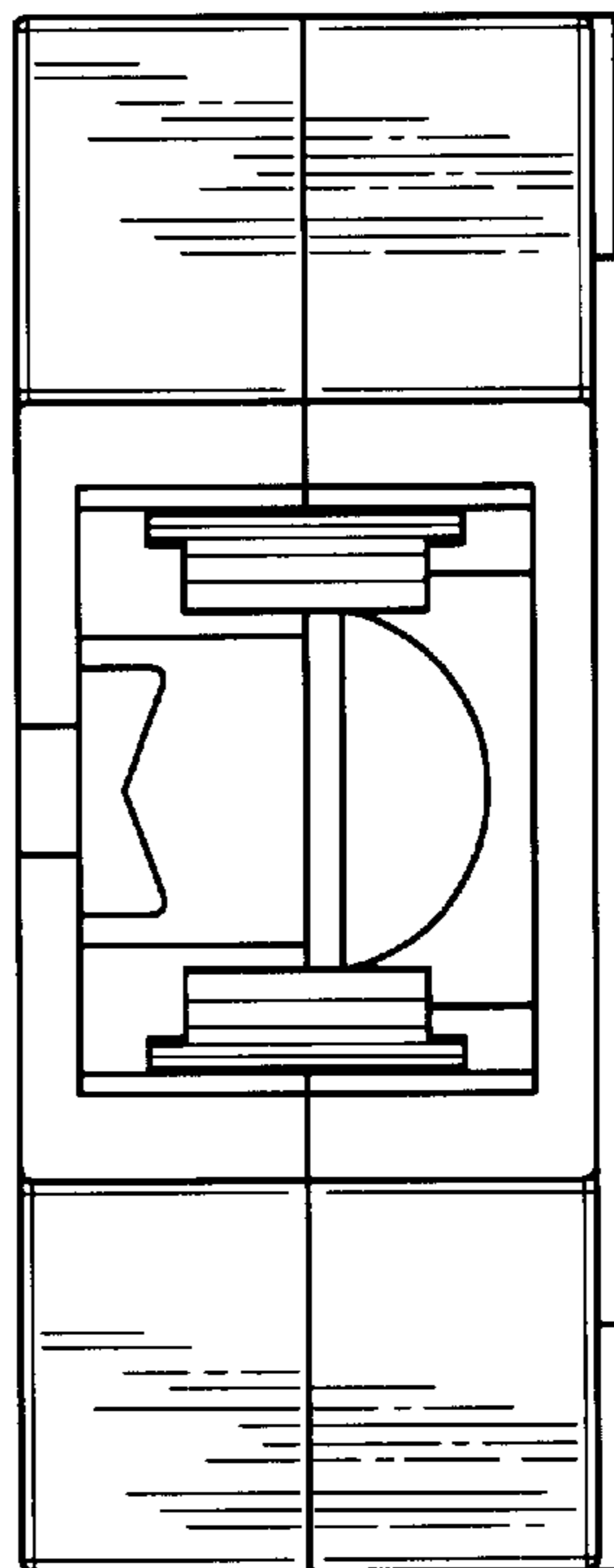


Fig. 4

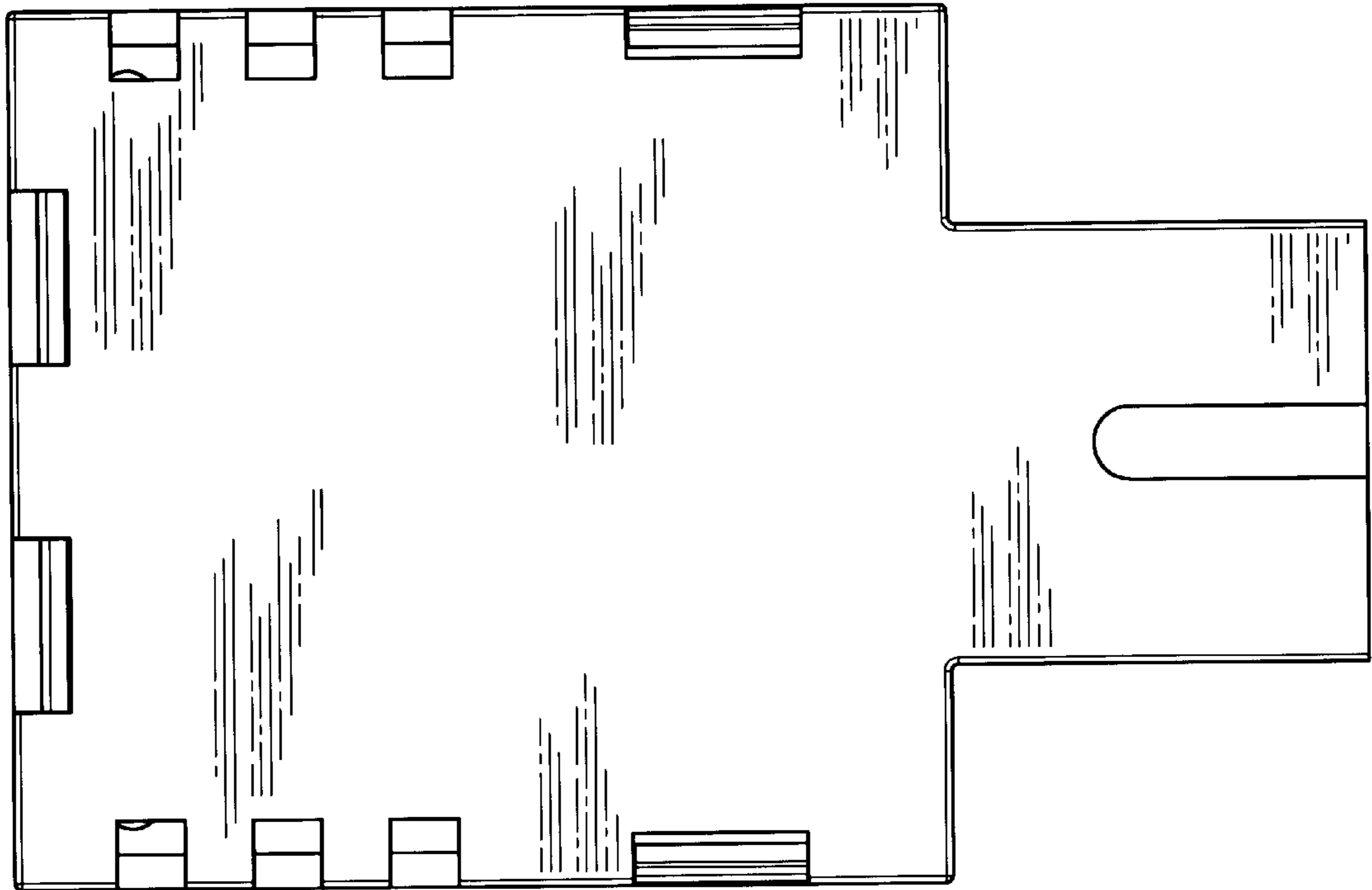


Fig. 5

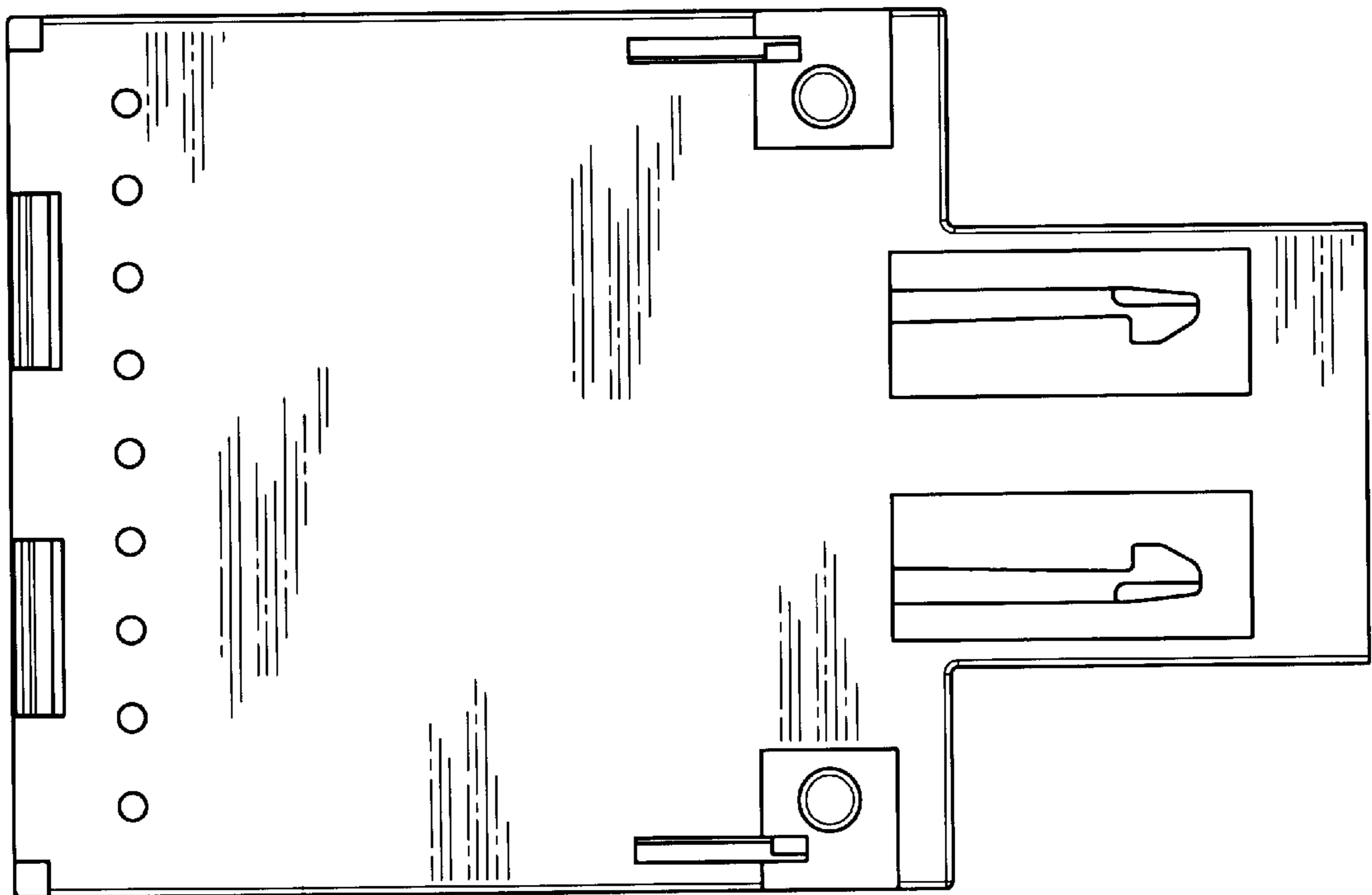


Fig. 6

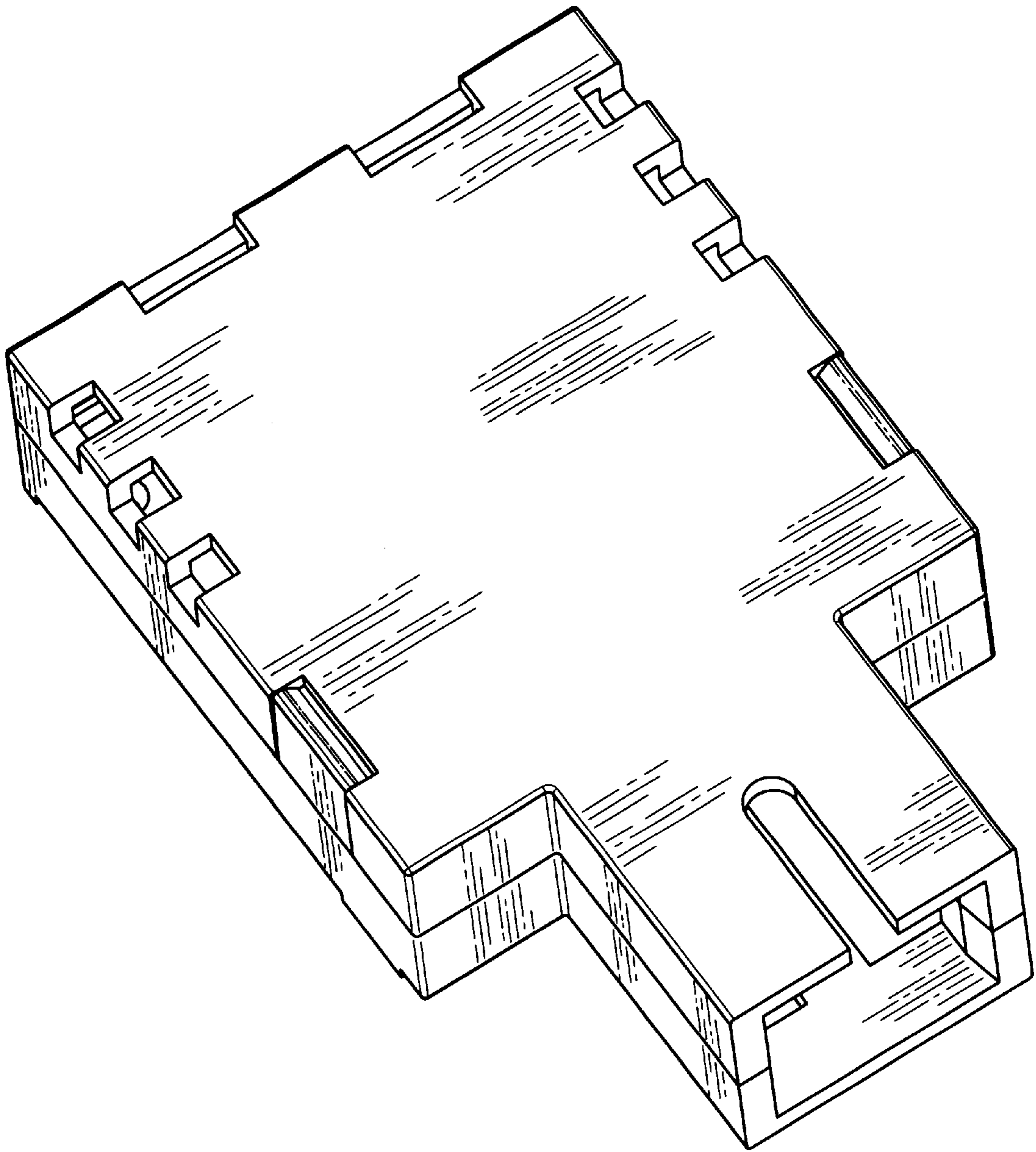


Fig. 7